


**APPLICATION DATA SHEET**

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	[FLIP-CHIP DIE AND FLIP-CHIP PACKAGE SUBSTRATE]		
Application Type : regular, utility			
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Customer Number:		31561	
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as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.